

Ceramic, High Q, Microwave (CBR), 0.3 pF, +/-0.1 pF, 250 V, 0603, COG, SMD, Fixed, RF, Ultra High Q, Low ESR, Class I



General Information	
Style:	SMD Chip
Series:	Microwave (CBR)
Chip Size:	0603
Description:	SMD, Fixed, RF, Ultra High Q, Low ESR, Class I
Features:	Ultra High Q, Low ESR, Class I
RoHS:	Yes
Termination:	Tin
Marking:	No
Miscellaneous:	Minimum Q = 806
Notes:	Solder Wave or Solder Reflow

Dimensions	
L	1.6mm +/-0.1mm
W	0.8mm +/-0.1mm
T	0.8mm +/-0.07mm
B	0.4mm +/-0.15mm

Packaging Specifications	
Packaging:	T&R, 180mm, Plastic Tape
Packaging Quantity:	4000

Specifications	
Capacitance:	0.3 pF
Capacitance Tolerance:	+/-0.1 pF
Voltage DC:	250 VDC
Dielectric Withstanding Voltage:	500 V
Temperature Range:	-55/+125C
Temperature Coefficient:	COG
Dissipation Factor:	0.246%
Aging Rate:	0% Loss/Decade Hour
Insulation Resistance:	10 GOhms
Quality Factor:	806

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